## Module Specifications

Thermoelectric material parameter tolerance is +/-10%.

<table>
<thead>
<tr>
<th>Material Specifications (27 °C hot side temperature)</th>
<th>Material Specifications (50 °C hot side temperature)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Vmax (V)</td>
<td>24.9</td>
</tr>
<tr>
<td>Imax (A)</td>
<td>6.1</td>
</tr>
<tr>
<td>Qmax (W)</td>
<td>94.0</td>
</tr>
<tr>
<td>DTmax (°C)</td>
<td>70</td>
</tr>
</tbody>
</table>

| Operation/storage temperature | -40 °C to +80 °C |

In no case should the module temperature be allowed to exceed its maximum operation/storage temperature.

Please review all product and technical information, Thermoelectric Module Mounting Procedure, parameter definitions, FAQ's, and ordering information posted on our website before purchasing or using this product.

### Optional Features and Notes:

- Add "P" to part number for sealing module with epoxy potting.
- Performance graphs include thermal resistance of substrates.

### Specifications

- **Width, A (mm)**: 40 +0.5/-0.2
- **Width, B (mm)**: 40 +0.5/-0.2
- **Height, H (mm)**: 4.1 ±0.05
- **Flatness, F (mm)**: 0.02
- **Parallelism, P (mm)**: 0.03
- **Wire Size, WS (mm²)**: 0.35
- **Wire Length, WL (mm)**: 120

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**NOTE:** All specifications are subject to change without notice. © 2018 TE Technology, Inc.
Unpotted HP-199-1.4-1.5 at a hot-side temperature of 30 °C
Potted HP-199-1.4-1.5 at a hot-side temperature of 30 °C

Note: All specifications subject to change without notice.

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Unpotted HP-199-1.4-1.5 at a hot-side temperature of 50 °C
Potted HP-199-1.4-1.5 at a hot-side temperature of 50 °C

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Unpotted HP-199-1.4-1.5 at a hot-side temperature of 70 °C

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Potted HP-199-1.4-1.5 at a hot-side temperature of 70 °C